REFLOW SOLDERING CONDITIONS 回流焊條件

☐ Applicable to Chip Type Aluminum Electrolytic Capacitors 適用於貼片式鋁電解電容器

■ Recommended Conditions for Reflow Soldering 推薦回流焊條件

(1) A thermal condition system such as infrared radiation (IR) or hot blast shall be adopted, and vapor heat transfer systems(VPS) are not recommended.
應采用紅外線或熱風回流焊接，而不宜采用汽相加熱回流焊接。

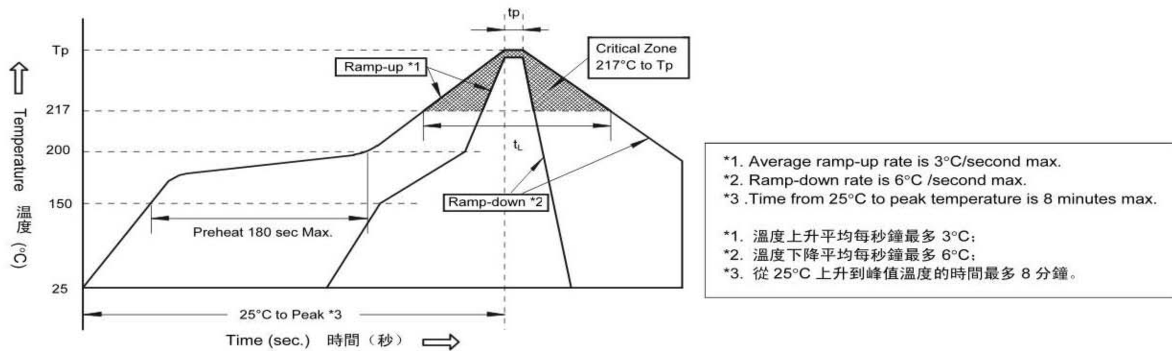
(2) Reflow soldering shall be done within 2 cycles. Please make sure that the parts have enough cooling time.
回流焊次數最多 2 次，請確保在第一次和第二次之間產品有足夠的冷卻時間。

(3) ■ The time of preheating from 150℃ to 200℃ shall be within 180 seconds;
從 150℃ 至 200℃的預熱時間在 180 秒以內；

■ The time of soldering temperature at 217℃ measured on capacitors' top shall not exceed t_L (second);
電容器頂部溫度超過 217℃的焊接時間不得超過 t_L（秒）；

■ The peak temperature on capacitors' top shall not exceed Tp(℃), and the time within 5℃ of actual peak temperature shall not exceed tp (second).
電容器頂部的峰值溫度不得超過 Tp(℃)，在 5℃範圍內的實際峰值溫度時間不得超過 tp(秒)。

■ **Classification Reflow Profile 回流焊曲線圖**

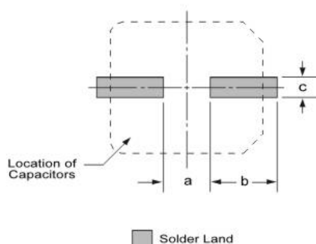


■ **Classified at Temperature and Time Only for Standard Size without ( )**
溫度和時間分類只適用於沒有（）的標準尺寸產品

Size 尺寸	Thickness(mm) 厚度	Volume(mm^3) 體積	Tp (℃)	t_L (second 秒)	Tp (second 秒)
Φ4～Φ6.3, Φ8×6.2L	≥2.5	＜350	250±0	60	5
Φ8×10.5L	≥2.5	350～2000	240±0	60	5
Φ10×10.5L/13.5L	≥2.5	350～2000	235±0	60	5
Φ12.5, Φ16	≥2.5	＞2000	230±0	30(20*)	5

Re: (20*) is special for mid-to-high voltage which is HU series. 注：(20*)爲針對中高壓 HU 系列產品

■ Recommended Solder Land Size no PC Board(Unit: mm) 推薦安裝尺寸



Size 尺寸	a	b	c
Ø4	1.0	2.6	1.6
Ø5	1.4	3.0	1.6
Ø6.3	2.1	3.5	1.6
Ø8×6.2L	2.1	4.5	1.6
Ø8×10.5L	3.0	3.5	2.5
Ø10	4.0	4.0	2.5
Ø12.5	4.0	5.7	3.0
Ø16	6.0	6.5	3.5

NOTE: All designs and specifications are for reference only and are subject to change without prior notice. If any doubt about safety for your application, please contact us immediately for technical assistance before purchase.

注: 以上所提供的設計及特性參數僅供參考作用，任何修改不作預先通知。如果在使用上有疑問，請在采購前與我們聯絡，以便提供技術上的協助。

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